

ENERGY BEAM CURABLE HYDROPHILIC PRESSURE SENSITIVE
ADHESIVE COMPOSITION AND USE THEREOF

ABSTRACT -

Disclosed herein is an energy beam curable hydrophilic pressure sensitive adhesive composition comprising a polymer (A) having an energy beam
5 polymerizable group and an acid group and a neutralizer
(B). Thus, a pressure sensitive adhesive composition suitable for use in a wafer surface protective sheet is provided. The wafer surface protective sheet protects a circuit pattern formed on a wafer surface from grinding
10 dust, etc. at the time of grinding the back of the wafer. The pressure sensitive adhesive composition can easily be removed by washing with water, even if the pressure sensitive adhesive remains on the wafer surface after peeling of the pressure sensitive adhesive sheet.



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